



Dr. SeungWoo Choi

(Tokyo Electron Korea, Korea)



Dr. SeungWoo Choi is fellow in Tokyo Electron Korea. Before he joined Tokyo Electron Korea, he has worked for Process Development team at Samsung Electronics and EVG for 10 and 6 years respectively. His major field is to develop wafer bonding technologies for 3D integration to apply to not only in fab devices like CIS, NAND, DRAM and Logic but also advanced package.

He received his B.S., M.S. and Ph.D. degrees in the Department of Materials Science and Engineering at Korea University in 1997, 1999 and 2003 respectively.

The title of Ph. D. thesis is “A study on the fabrication and characterization of bonded SOI wafers with Al₂O₃ buried layers.”